

CERTIFICATE OF TRANSMISSION BY FACSIMILE (37 CFR 1.8)Applicant(s): **Tai-Chong CHAI et al.**

Docket No.

66286-0002

Serial No.

09/497,421

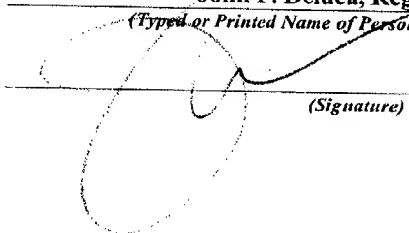
Filing Date

February 2, 2000

Examiner

L. Cruz

Group Art Unit

2815Invention: **LEAD FRAME FOR AN INTEGRATED CIRCUIT CHIP (SMALL WINDOW)**I hereby certify that this Amendment*(Identify type of correspondence)*is being facsimile transmitted to the United States Patent and Trademark Office (Fax. No. 703-308-7722)on February 27, 2003*(Date)*John P. Deluca, Reg. No. 25,505*(Typed or Printed Name of Person Signing Certificate)*
*(Signature)***Note: Each paper must have its own certificate of mailing.**

66286-0002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Tai-Chong CHAI *et al.*

Serial No.: 09/497,421

Filed: February 2, 2000

For: LEAD FRAME FOR AN INTEGRATED
CIRCUIT CHIP (SMALL WINDOW)

Group Art Unit: 2815

Examiner: L. Cruz

February 26, 2003

Commissioner for Patents
Washington, D.C. 20231

Via Facsimile
703- 308-7722

Sir:

AMENDMENT

In response to the Office Action of August 27, 2002, please amend the Application as follows:

IN THE CLAIMS

Please amend claims 1 and 12 as follows:

1. (Amended) A lead frame, for an integrated circuit chip having a frame engaging bottom surface for attachment to the frame by means of a chip attach material, said chip being formed with outer edges having defined dimensions, said frame comprising:
a unitary apertured frame having a central through aperture therein including a plurality of uniform sidebars each having an upper chip-supporting surface for engaging the bottom of the surface of the chip with the chip attach material therebetween,
each of said sidebars having an inner edge and an outer edge, said inner edges defining the central aperture,
said inner and outer edges being uniformly spaced apart defining therebetween a chip-support zone [for the frame] having defined dimensions,